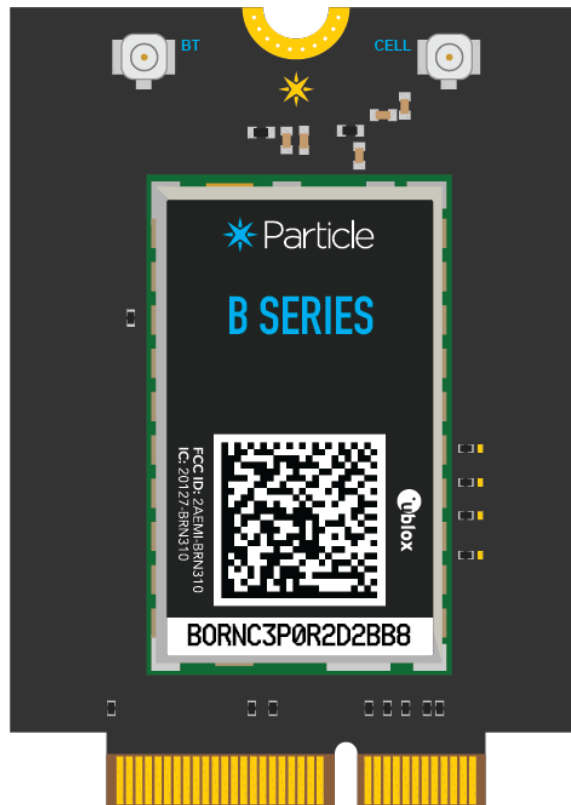


# B402 Datasheet (004)



# Functional description

## OVERVIEW

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The B Series System-on-a-Module (SoM) is a cellular device with support for BLE (Bluetooth LE). It is based on the Nordic nRF52840 micro-controller.

The B Series is designed to be integrated into your circuit board design, plugging into a M.2 NGFF connector on your board, allowing the module to be changed or upgraded easily.

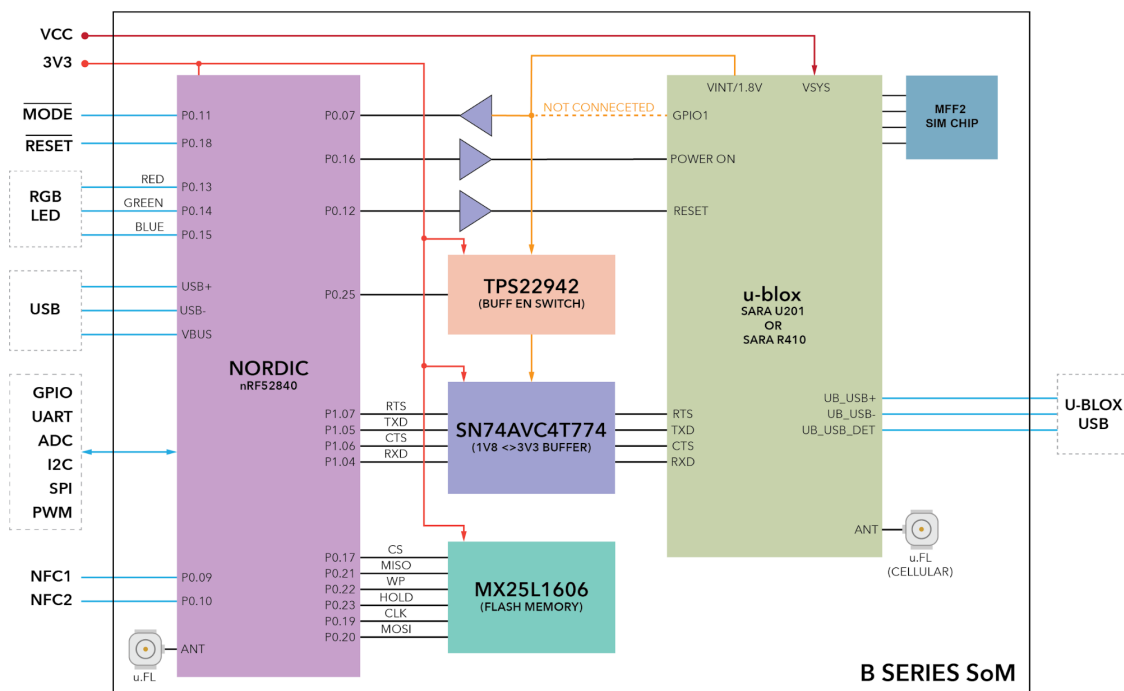
## FEATURES

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- u-blox SARA-R410-02B LTE modem
  - LTE Cat M1 module with global hardware support (MVNO support for US only)
  - 3GPP Release 13 LTE Cat M1
  - Cat M1 bands: 2, 3, 4, 5, 8, 12, 13, 20, 28
- Nordic Semiconductor nRF52840 SoC
  - ARM Cortex-M4F 32-bit processor @ 64MHz
  - 1MB flash, 256KB RAM
  - Bluetooth 5: 2 Mbps, 1 Mbps, 500 Kbps, 125 Kbps
  - Supports DSP instructions, HW accelerated Floating Point Unit (FPU) calculations
  - ARM TrustZone CryptoCell-310 Cryptographic and security module
  - Up to +8 dBm TX power (down to -20 dBm in 4 dB steps)
  - NFC-A tag
- On-module additional 4MB SPI flash
- 24 mixed signal GPIO (8 x Analog, 4 x PWM), UART, I2C, SPI
- USB 2.0 full speed (12 Mbps)
- JTAG (SWD) pins
- RGB status pins for LED
- Reset and Mode pins for buttons
- On-module MFF2 Particle SIM
- Two on-module U.FL connectors for external antennas
- M.2 interface
- FCC and PTCRB certified
- RoHS compliant (lead-free)

# Interfaces

## BLOCK DIAGRAM



## POWER

### VCC

VCC is used to supply power to the u-blox SARA-R410M cellular module. The recommended input voltage range on this pin is between 3.6V to 4.2V DC. Make sure that the supply can handle currents of at least 2 A.

### 3V3

3V3 is used to supply power to nRF52840, logic ICs, memory, etc. and 3.3v is recommended. VCC input voltage range is between 3V to 3.6V DC. Make sure that the supply can handle currents of at least 150mA.

### VBus

VBus is connected to the USB detect pin of nRF52840 to enables the USB interface. The recommended input voltage range is between 4.35V to 5.5V DC.

## ANTENNA

---

There are two radios on the B402 module. A BLE radio (nRF52840) and a cellular radio (u-blox). We have provided two u.FL connectors to plug in the cellular and BLE antenna. These are required if you wish to use the cellular and BLE. If you do not need BLE, you do not need to connect the BLE antenna.

### Certified Cellular Antenna

SKU	Description
ANTCW2EA	Particle Cellular Flex Antenna 2G/3G/LTE [x1]
ANTCW2TY	Particle Cellular Flex Antenna 2G/3G/LTE Tray of 50 [x50]

- Type: LTE Ultra Wide Band Flex Antenna
- Frequency/band: 698 MHz-2690 MHz
- RoHS Compliant
- Mechanical Specs:
  - Dimensions: 97 x 21 x 0.2 mm
  - Mounting: 3M adhesive backed for application on non-metallic surfaces
  - Connector type: FPC + IPEX connector
  - Cable length: 210 mm
  - Gain: 4.71 dBi

### General Antenna Guidance

- The antenna placement needs to follow some basic rules, as any antenna is sensitive to its environment. Mount the antenna at least 10mm from metal components or surfaces, ideally 20mm for best radiation efficiency, and try to maintain a minimum of three directions free from obstructions to be able to operate effectively.
- Needs tuning with actual product enclosure and all components.
- For the BLE antenna, it is recommended to use a 2.4 GHz single-frequency antenna and not a 2.4 GHz + 5 GHz antenna, so as to avoid large gain at the frequency twice of 2.4 GHz which can cause the second harmonic radiation of 2.4 GHz to exceed standards.

## PERIPHERALS AND GPIO

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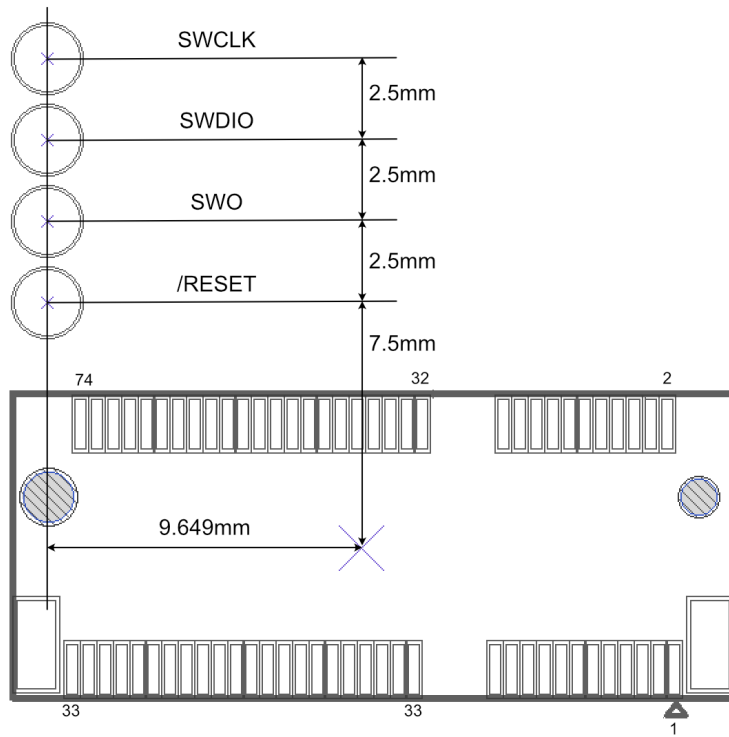
Peripheral Type	Qty	Input(I) / Output(O)
Digital	24 (max)	I/O
Analog (ADC)	8 (max)	I
UART	1	I/O
SPI	2	I/O
I2C	2	I/O
USB	1	I/O
PWM	7 (max)	O
NFC	1	O

There are some optional B402 module specific I/O:

- u-blox USB and VBUS (for u-blox firmware upgrades)

**Note:** All GPIOs are only rated at 3.3VDC max.

The B402 module has 4 pads at the bottom exposing the SWD interface of the nRF52840. This interface can be used to debug your code or reprogram your E402 bootloader, device OS, or the user firmware. We use 4 pogo-pins connecting to these pads during production for firmware flashing.



# Memory map

## **NRF52840 FLASH LAYOUT OVERVIEW**

---

- Bootloader (48KB, @0xF4000)
- User Application (128KB, @0xD4000)
- System (656KB, @0x30000)
- SoftDevice (192KB)

## **EXTERNAL SPI FLASH LAYOUT OVERVIEW (DFU OFFSET: 0X80000000)**

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- OTA (1500KB, @0x00289000)
- Reserved (420KB, @0x00220000)
- FAC (128KB, @0x00200000)
- LittleFS (2M, @0x00000000)

# Pins and button definitions

## PINOUT DIAGRAM

	H1	H3	
	H5		
VCC	2	1	GND
VCC	4	3	GND
VCC	6	5	GND
VCC	8	7	GND
3V3	10	9	GND
3V3	12	11	USB D+
RESERVED	14	13	USB D-
VUSB	16	15	GND
RESERVED	18	17	NFC1
SCL	20	19	NFC2
SDA	22	21	GND
KEY	23		ADC0
MODE	32	33	ADC1
RESET	34	35	ADC2
TX	36	37	ADC3
RX	38	39	AGND
CTS	40	41	ADC4
RTS	42	43	ADC5
u-blox USB+	44	45	ADC6
u-blox USB-	46	47	ADC7
CS	48	49	AGND
MISO	50	51	RESERVED
MOSI	52	53	RESERVED
SCK	54	55	RESERVED
GND	56	57	RESERVED
RESERVED	58	59	RESERVED
RESERVED	60	61	RED
GPIO0	62	63	GREEN
GPIO1	64	65	BLUE
PWM0	66	67	SIM_VCC
PWM1	68	69	SIM_RST
PWM2	70	71	SIM_CLK
PWM3	72	73	SIM_DATA
u-blox VBUS	74	75	NC
	H2	H4	

Pins SOM0 to SOM9 will vary across various SoM modules. For example, cellular-specific pins exists in this range.

Additionally there are RESERVED<sup>3</sup> pins, whose functions vary depending on the SoM. For example, nRF52 MCU-based modules use some of these pins for additional ADC and GPIO. They are able to be used as described on the B402, but their function may be different on future modules.

For maximum cross-module flexibility, you should try to use only the common pins when possible.

## PIN DESCRIPTION

#	Pin	Common	Function	nRF52	Description
1	GND	GND	POWER		System ground.
2	VCC	VCC	POWER		System power in, connect to the +LiPo or supply a fixed 3.6-4.2v power.
3	GND	GND	POWER		System ground.
4	VCC	VCC	POWER		System power in, connect to the +LiPo or supply a fixed 3.6-4.2v power.
5	GND	GND	POWER		System ground.
6	VCC	VCC	POWER		System power in, connect to the +LiPo or supply a fixed 3.6-4.2v power.
7	GND	GND	POWER		System ground.
8	VCC	VCC	POWER		System power in, connect to the +LiPo or supply a fixed 3.6-4.2v power.
9	GND	GND	POWER		System ground.
10	3V3	3V3	POWER		System power in, supply a fixed 3.0-3.6v power.

11	USB D+	USB D+	IO		Data+ pin of the NRF52840 USB port.
12	3V3	3V3	POWER		System power in, supply a fixed 3.0-3.6v power.
13	USB D-	USB D-	IO		Data- pin of the NRF52840 USB port.
14	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
15	GND	GND	POWER		System ground.
16	VUSB	VUSB	POWER		System power in, USB detect pin for nRF52840. 5V on this pin enables the USB interface.
17	NFC1	SOM3 <sup>3</sup>	NFC input	P0.9	NFC antenna connection.
18	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
19	NFC2	SOM4 <sup>3</sup>	NFC input	P0.10	NFC antenna connection.
20	D1	SCL	IO	P0.27	I2C SCL, and digital only GPIO.
21	GND	GND	POWER		System ground.
22	D0	SDA	IO	P0.26	I2C SDA, and digital only GPIO.
23	A0	ADC0	IO	P0.3	Analog input ADC0 <sup>2</sup> , and digital GPIO.
32	MODE	MODE	IO	P0.11	Connected to the MODE button input, and digital only GPIO.
33	A1	ADC1	IO	P0.4	Analog input ADC1 <sup>2</sup> , and digital GPIO.
34	RESET	RESET	I		Active-low reset input.
35	A2	ADC2	IO	P0.28	Analog input ADC2 <sup>2</sup> , and digital GPIO.
36	D9	TX	IO	P0.6	Primarily used as UART TX, but can also be used as a digital GPIO.
37	A3	ADC3	IO	P0.29	Analog input ADC3 <sup>2</sup> , and digital GPIO.
38	D10	RX	IO	P0.08	Primarily used as UART RX, but can also be used as a digital GPIO.
39	AGND	AGND	POWER		System analog ground.
40	D3	RESERVED <sup>3</sup>	IO	P1.1	UART flow control interface CTS, SCL1 (Wire1), SPI1 MOSI, and digital only GPIO.
41	A4	RESERVED <sup>3</sup>	IO	P0.30	Analog input ADC4 <sup>2</sup> , and digital GPIO.
42	D2	RESERVED <sup>3</sup>	IO	P1.2	UART flow control interface RTS, SDA1 (Wire1), SPI1 SCK, and digital only GPIO.
43	A5	RESERVED <sup>3</sup>	IO	P0.31	Analog input ADC5 <sup>2</sup> , and digital GPIO.
44	u-blox USB D+	SOM0	IO		Data+ pin of the R410M USB port.
45	A6	RESERVED <sup>3</sup>	IO	P0.5	Analog input ADC6 <sup>2</sup> , and digital GPIO.
46	u-blox USB D-	SOM1	IO		Data- pin of the R410M USB port.
47	A7	RESERVED <sup>3</sup>	IO	P0.2	Analog input ADC7 <sup>2</sup> , and digital GPIO.
48	D8	CS	IO	P1.3	SPI interface CS, and digital only GPIO.
49	AGND	AGND	POWER		System analog ground.
50	D11	MISO	IO	P1.14	SPI interface MISO, and digital only GPIO.
51	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
52	D12	MOSI	IO	P1.13	SPI interface MOSI, and digital only GPIO.
53	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
54	D13	SCK	IO	P1.15	SPI interface SCK, and digital only GPIO.
55	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
56	GND	GND	POWER		System analog ground.



57	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
58	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
59	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
60	NC	RESERVED <sup>3</sup>	NC		Leave unconnected.
61	RGBR	RED	IO	P0.13	Red pin of the RGB LED.
62	D22	GPIO0	IO	P0.24	GPIO0, digital only.
63	RGBG	GREEN	IO	P0.14	Green pin of the RGB LED.
64	D23	GPIO1	IO	P1.9	GPIO1, digital only.
65	RGBB	BLUE	IO	P0.15	Blue pin of the RGB LED.
66	D4	PWM0	IO	P1.8	SPI1 MISO, Digital only GPIO, and PWM0.
67	SIM_VCC <sup>1</sup>	SOM5 <sup>3</sup>	POWER		Leave unconnected, 1.8V/3V SIM Supply Output from R410M.
68	D5	PWM1	IO	P1.10	Digital only GPIO, and PWM1.
69	SIM_RST <sup>1</sup>	SOM6 <sup>3</sup>	IO		Leave unconnected, 1.8V/3V SIM Reset Output from R410M.
70	D6	PWM2	IO	P1.11	Digital only GPIO, and PWM2.
71	SIM_CLK <sup>1</sup>	SOM7 <sup>3</sup>	IO		Leave unconnected, 1.8V/3V SIM Clock Output from R410M.
72	D7	PWM3	IO	P1.12	Digital only GPIO, and PWM3.
73	SIM_DATA <sup>1</sup>	SOM8 <sup>3</sup>	IO		Leave unconnected, 1.8V/3V SIM Data I/O of R410m with internal 4.7 k pull-up.
74	u-blox VBUS	SOM2 <sup>3</sup>	IO		USB detect pin for R410M. 5V on this pin enables the u-blox USB interface.
75	NC	SOM9 <sup>3</sup>	NC		Leave unconnected.

<sup>1</sup>These pins are connected to the internal MFF2 SIM and should be left open.

<sup>2</sup>A0-A7 are 12-bit Analog-to-Digital (A/D) inputs (0-4095).

<sup>3</sup>SoM-specific and Reserved pins will vary depending on module. They are able to be used on the B402, but their function may be different on future modules.

## LED STATUS

### System RGB LED

Unlike the Boron, the B402 module does not have an on-module RGB system status LED. We have provided its individual control pins for you to connect an LED of your liking. This will allow greater flexibility in the end design of your products.

A detailed explanation of different color codes of the RGB system LED can be found [here](#).

# Technical specifications

## ABSOLUTE MAXIMUM RATINGS <sup>[1]</sup>

### Supply voltages

Parameter	Symbol	Min	Typ	Max	Unit
<b>Supply voltages</b>					
Supply Input Voltage	VCC	-0.3		+6.0	V
Supply Input Voltage	3V3	-0.3		+3.9	V
VBUS USB supply voltage	VUSB	-0.3		+5.8	V
<b>I/O pin voltage</b>					
VI/O, VDD ≤ 3.6 V	IO	-0.3		VDD + 0.3	V
VI/O, VDD > 3.6 V	IO	-0.3		+3.9	V
<b>NFC antenna pin current</b>					
I <sub>NFC1/2</sub>	NFC1/NFC2			80	mA
<b>Radio</b>					
BT RF input level (52840)				10	dBm
<b>Environmental</b>					
Storage temperature		-40		+85	°C

<sup>[1]</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit
<b>Supply voltages</b>					
Supply Input Voltage	VCC	+3.6	+3.8	+4.2	V
Supply Input Voltage	3V3	+3.0	+3.3	+3.6	V
VBUS USB supply voltage	VUSB	+4.35	+5.0	+5.5	V
<b>Environmental</b>					
Normal operating temperature <sup>1</sup>		-20	+25	+65	°C
Extended operating temperature <sup>2</sup>		-40		+85	°C
Humidity Range Non condensing, relative humidity				95	%

### Notes:

<sup>1</sup> Normal operating temperature range (fully functional and meet 3GPP specifications).

<sup>2</sup> Extended operating temperature range (RF performance may be affected outside normal operating range, though module is fully functional)

**POWER CONSUMPTION**

Parameter	Symbol	Min	Typ	Max	Unit
Operating Current (uC on, peripherals and radio disabled)	I <sub>idle</sub>	4.48	4.71	5.17	mA
Operating Current (uC on, cellular on but not connected)	I <sub>cell_idle</sub>	TBD	TBD	TBD	mA
Operating Current (uC on, cellular connecting to tower)	I <sub>cell_conn_twr</sub>	TBD	TBD	TBD	mA
Operating Current (uC on, cellular connecting to cloud)	I <sub>cell_conn_cloud</sub>	TBD	TBD	TBD	mA
Operating Current (uC on, cellular connected but idle)	I <sub>cell_cloud_idle</sub>	TBD	TBD	TBD	mA
Operating Current (uC on, cellular connected and transmitting)	I <sub>cell_cloud_tx</sub>	TBD	TBD	TBD	mA
STOP mode sleep, GPIO wake-up	I <sub>stop_gpio</sub>	552	555	559	uA
STOP mode sleep, analog wake-up	I <sub>stop_analog</sub>	554	557	559	uA
STOP mode sleep, RTC wake-up	I <sub>stop_intrtc</sub>	553	556	558	uA
STOP mode sleep, BLE wake-up, advertising	I <sub>stop_ble_adv</sub>		631	2650	uA
STOP mode sleep, BLE wake-up, connected	I <sub>stop_ble_conn</sub>	47.3	630	1540	uA
STOP mode sleep, serial wake-up	I <sub>stop_usart</sub>	553	556	558	uA
STOP mode sleep, cellular wake-up	I <sub>stop_cell</sub>	8.87	9.65	63.6	mA
ULP mode sleep, GPIO wake-up	I <sub>ulp_gpio</sub>	44.7	47.6	49.6	uA
ULP mode sleep, analog wake-up	I <sub>ulp_analog</sub>	45.0	47.8	49.5	uA
ULP mode sleep, RTC wake-up	I <sub>ulp_intrtc</sub>	43.4	46.4	47.9	uA
ULP mode sleep, BLE wake-up, advertising	I <sub>ulp_ble_adv</sub>		130	2560	uA
ULP mode sleep, BLE wake-up, connected	I <sub>ulp_ble_conn</sub>		121	1010	uA
ULP mode sleep, serial wake-up	I <sub>ulp_usart</sub>	554	557	559	uA
ULP mode sleep, cellular wake-up	I <sub>ulp_cell</sub>	0.37	9.47	53.7	mA
HIBERNATE mode sleep, GPIO wake-up	I <sub>hib_gpio</sub>	23.6	26.0	29.7	uA
HIBERNATE mode sleep, analog wake-up	I <sub>hib_analog</sub>	23.9	26.5	30.5	uA

## RADIO SPECIFICATIONS

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Boron has two radio modules.

### nRF52840

- Bluetooth® 5, 2.4 GHz
  - 95 dBm sensitivity in 1 Mbps Bluetooth® low energy mode
  - 103 dBm sensitivity in 125 kbps Bluetooth® low energy mode (long range)
  - 20 to +8 dBm TX power, configurable in 4 dB steps

### u-blox SARA-R410M-02-B

Parameter	Value
Protocol stack	3GPP Release 13
RAT	LTE Cat M1 Half-Duplex
LTE FDD Bands	Band 12 (700 MHz)
	Band 17 (700 MHz)
	Band 28 (700 MHz)
	Band 13 (750 MHz)
	Band 20 (800 MHz)
	Band 26 (850 MHz)
	Band 18 (850 MHz)
	Band 5 (850 MHz)
	Band 19 (850 MHz)
	Band 8 (900 MHz)
	Band 4 (1700 MHz)
	Band 3 (1800 MHz)
	Band 2 (1900 MHz)
	Band 25 (1900 MHz)
	Band 1 (2100 MHz)
LTE TDD bands	Band 39 (1900 MHz)
Power class	Class 3 (23 dBm)

## I/O CHARACTERISTICS

These specifications are based on the nRF52840 datasheet.

Symbol	Parameter	Min	Typ	Max	Unit
VIH	Input high voltage	0.7 xVDD		VDD	V
VIL	Input low voltage	VSS		0.3 xVDD	V
VOH,SD	Output high voltage, standard drive, 0.5 mA, VDD ≥1.7	VDD - 0.4		VDD	V
VOH,HDH	Output high voltage, high drive, 5 mA, VDD ≥ 2.7 V	VDD - 0.4		VDD	V
VOH,HDL	Output high voltage, high drive, 3 mA, VDD ≥ 1.7 V	VDD - 0.4		VDD	V
VOL,SD	Output low voltage, standard drive, 0.5 mA, VDD ≥1.7	VSS		VSS + 0.4	V
VOL,HDH	Output low voltage, high drive, 5 mA, VDD ≥ 2.7 V	VSS		VSS + 0.4	V
VOL,HDL	Output low voltage, high drive, 3 mA, VDD ≥ 1.7 V	VSS		VSS + 0.4	V
IOL,SD	Current at VSS+0.4 V, output set low, standard drive, VDD ≥1.7	1	2	4	mA
IOL,HDH	Current at VSS+0.4 V, output set low, high drive, VDD ≥ 2.7V	6	10	15	mA
IOL,HDL	Current at VSS+0.4 V, output set low, high drive, VDD ≥ 1.7V	3			mA
IOH,SD	Current at VDD-0.4 V, output set high, standard drive, VDD ≥1.7	1	2	4	mA
IOH,HDH	Current at VDD-0.4 V, output set high, high drive, VDD ≥ 2.7V	6	9	14	mA
IOH,HDL	Current at VDD-0.4 V, output set high, high drive, VDD ≥ 1.7V	3			mA
tRF,15pF	Rise/fall time, standard drivemode, 10-90%, 15 pF load <sup>1</sup>		9		ns
tRF,25pF	Rise/fall time, standard drive mode, 10-90%, 25 pF load <sup>1</sup>		13		ns
tRF,50pF	Rise/fall time, standard drive mode, 10-90%, 50 pF load <sup>1</sup>		25		ns
tHRF,15pF	Rise/Fall time, high drive mode, 10-90%, 15 pF load <sup>1</sup>		4		ns
tHRF,25pF	Rise/Fall time, high drive mode, 10-90%, 25 pF load <sup>1</sup>		5		ns
tHRF,50pF	Rise/Fall time, high drive mode, 10-90%, 50 pF load <sup>1</sup>		8		ns
RPU	Pull-up resistance	11	13	16	kΩ
RPD	Pull-down resistance	11	13	16	kΩ
CPAD	Pad capacitance		3		pF
CPAD_NFC	Pad capacitance on NFC pads		4		pF
INFC_LEAK	Leakage current between NFC pads when driven to different states		1	10	μA

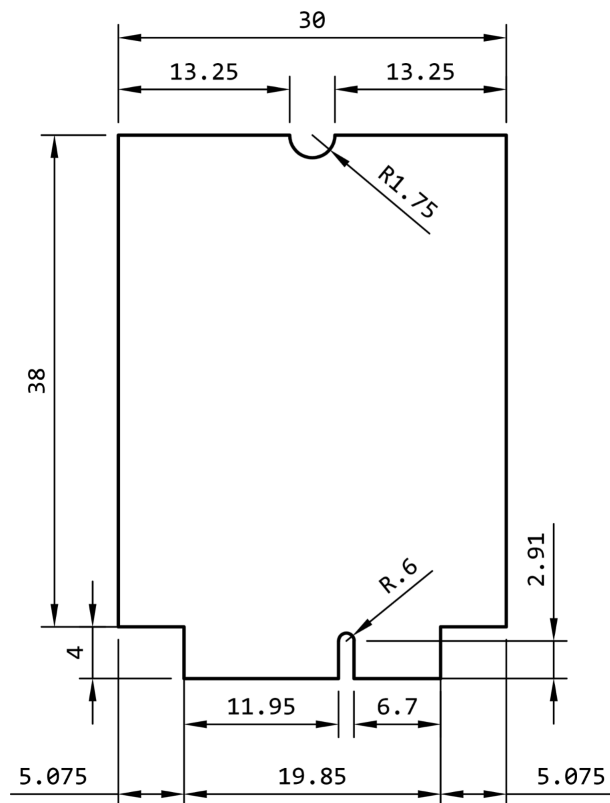
- Rise and fall times based on simulations
- GPIO default to standard drive (2mA) but can be reconfigured to high drive (9mA) in Device OS 2.0.0 and later using the `pinSetDriveStrength()` function.

## Mechanical specifications

## DIMENSIONS AND WEIGHT

Parameters	Value	Unit
Width	30	mm
Height	42	mm
Thickness	5.5	mm
Weight	6.2	grams

## MECHANICAL DRAWING

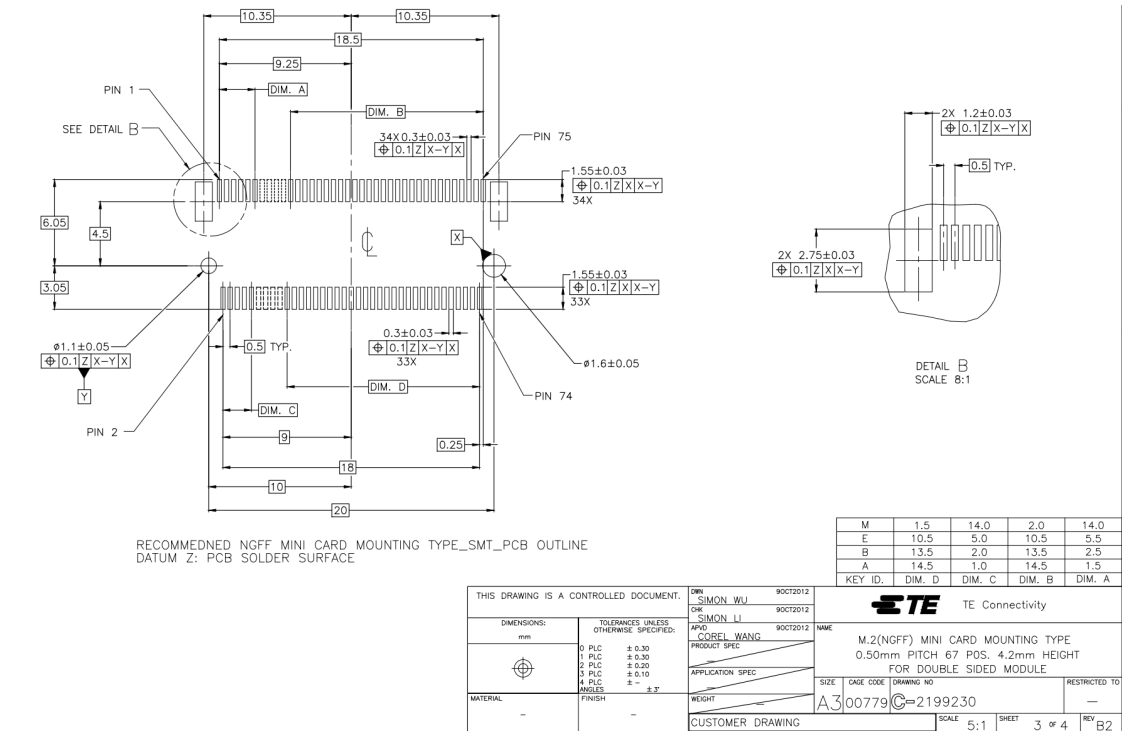


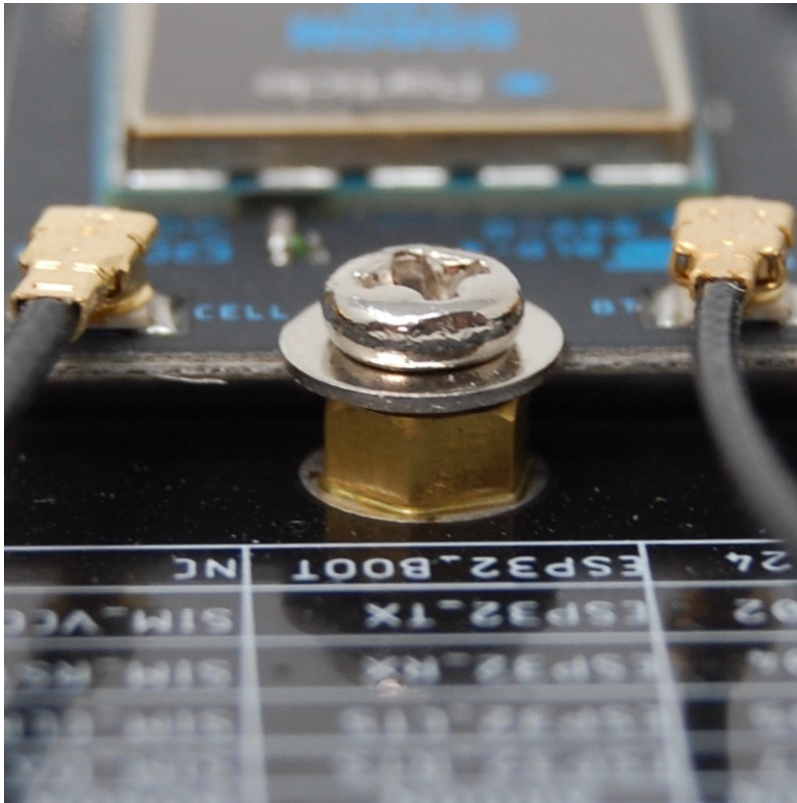
Dimensions are in millimeters.

MATING CONNECTOR AND LAND PATTERN

The mating connector is a an M.2 (NGFF) type 4. Note that there are several different key configurations for the M.2, and type 4 is different than is commonly used on SSDs.

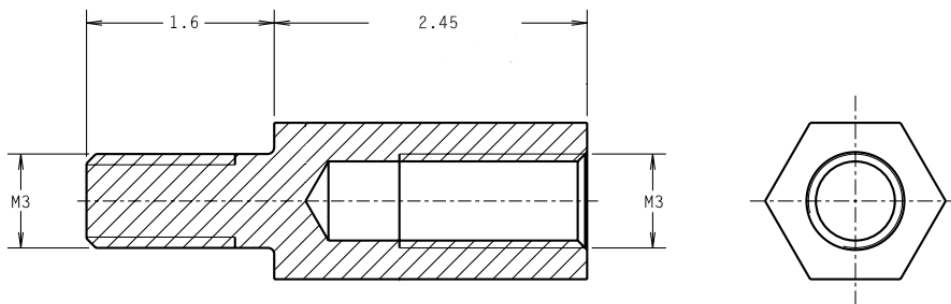
One compatible connector is the [TE 2199230-4](#). It is widely available including at suppliers such as [DigiKey](#).





We recommend this screw assembly to securely affix the B series SoM to your circuit board. From top to bottom:

- M3 screw, 3mm long
- M3 washer
- M3 standoff, 2.45mm



- Mounting hole, 2.6 mm metal hole, 3.1mm metal ring diameter (picture is of the bottom side of the circuit board)



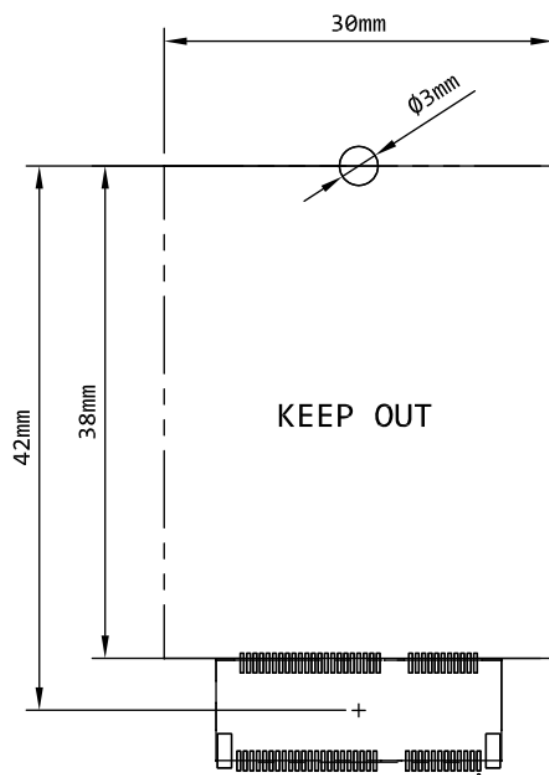


- An [alternative design](#) uses a [JAE SM3ZS067U410-NUTI-R1200](#) standoff. It's reflow soldered to your base board and has a threaded hole for a M2\*3 screw to hold down the SoM. This may be easier to obtain.
- Note that a hold-down screw is required because the M.2 connector does not have integrated locks and the SoM will pop up if not attached to the base board.

#### **DESIGN CONSIDERATIONS**

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We strongly recommend against placing components under the SOM board because there is not enough height.



# Product Handling

## **ESD PRECAUTIONS**

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The B series contains highly sensitive electronic circuitry and is an Electrostatic Sensitive Device (ESD). Handling an B series without proper ESD protection may destroy or damage it permanently. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any application that incorporates the B series module. ESD precautions should be implemented on the application board where the B series is mounted. Failure to observe these precautions can result in severe damage to the B series!

## **CONNECTORS**

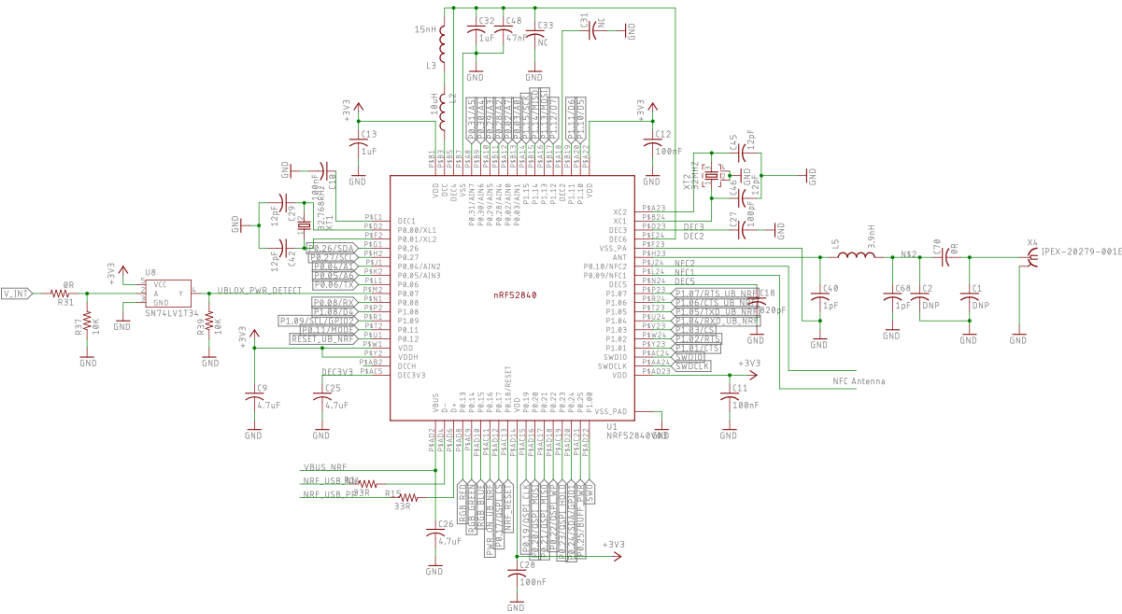
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The U.FL antenna connector is not designed to be constantly plugged and unplugged. The antenna pin is static sensitive and you can destroy the radio with improper handling. A tiny dab of glue (epoxy, rubber cement, liquid tape or hot glue) on the connector can be used securely hold the plug in place.

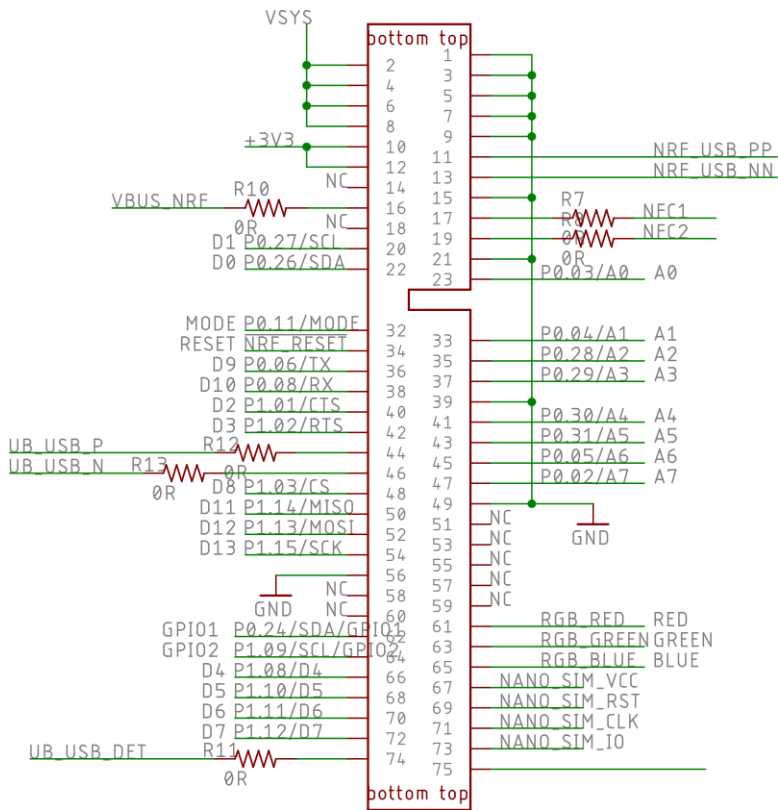
The M.2 edge connector is static sensitive and should be handled carefully. The M.2 connector is not designed for repeated removal and insertion of the module.

# Schematics

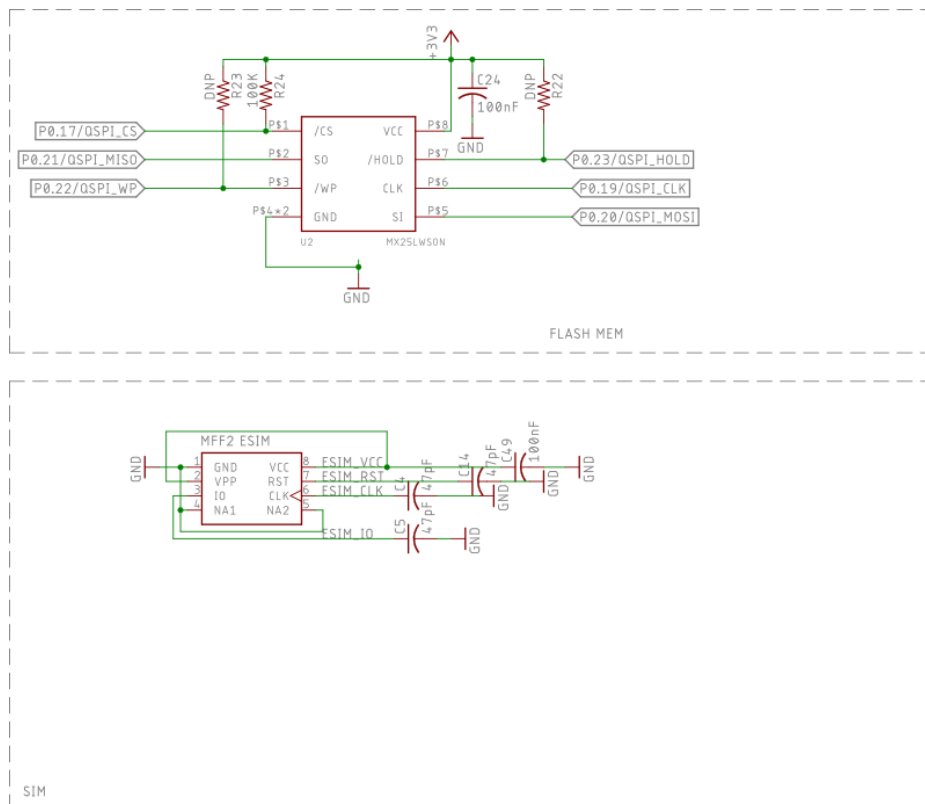
## MICROCONTROLLER



## M.2 CONNECTOR



## SIM AND FLASH



## Default settings

The B series comes pre-programmed with a bootloader and a user application called Tinker. This application works with an iOS and Android app also named Tinker that allows you to very easily toggle digital pins, take analog and digital readings and drive variable PWM outputs.

The bootloader allows you to easily update the user application via several different methods, USB, OTA, Serial Y-Modem, and also internally via the Factory Reset procedure. All of these methods have multiple tools associated with them as well.

## Revision history

Revision	Date	Author	Comments
001	29 Apr 2019	RK	Initial Release
002	03 Feb 2020	RK	Fixed number of I2C, SPI, and PWM
003	18 Feb 2020	RK	Keep-out diagram M.2 connector was upside-down
004	16-Sep-2020	RK	Added power consumption information